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Attorney Docket No. MTI-31607



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Lee, Teck Kheng
Serial No. : 10/050,507
Filing Date : January 16, 2002
For : Elimination of RDL Using Tape Base Flip Chip on Flex for Die Stacking

Assistant Commissioner for Patents
Washington, D.C. 20231

**POWER OF ATTORNEY BY ASSIGNEE
AND CERTIFICATE UNDER 37 CFR § 3.73(b)**

Sir:

MICRON TECHNOLOGY, INC., assignee of the entire right, title and interest by assignment from the inventor(s) in the above-identified application, hereby appoints the following attorneys and agents:

Gary R. Plotecher, Reg. No. 27830
Alan E. Wagner, Reg. No. 45188
Alexander R. Kuszewski, Reg. No. 41920
Charles B. Brantley, II, Reg. No. 38086
William H. Dietrich, Reg. No. 48359

Kristine M. Strodthoff, Reg. No. 34259
Thomas J. Pienkos, Reg. No. 46992
Elisabeth T. Bridge, Reg. No. 37523
Michael L. Lynch, Reg. No. 30871

as its attorneys with full power of substitution to prosecute this application and all applications claiming filing date priority therefrom and to transact all business in the U.S. Patent and Trademark Office in connection therewith.

The above-identified assignee hereby elects, pursuant to 37 CFR §3.71, to conduct the prosecution of the above-identified patent application to the exclusion of the inventor(s).

A chain of title from the inventor(s) of the above-identified patent application to the above-identified assignee is shown:

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- ☐ In an assignment recorded in the U.S. Patent and Trademark Office at Reel ____,
Frame ____.
- ☒ In an assignment filed herewith for recordation, a true copy of which is attached
hereto.

The undersigned has reviewed the above-identified assignment and, to the best of his
knowledge and belief, title is in the above-identified assignee.

The undersigned further avers that he is empowered to make and sign the foregoing
certification on behalf of the above-identified assignee, and to take the action set further herein
on its behalf.

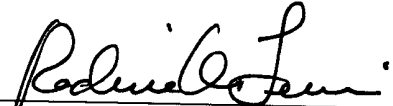
Please direct all communications regarding the above-identified application to:

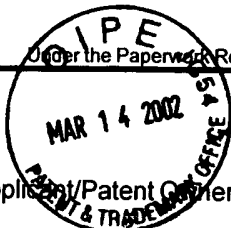
Kristine M. Strodthoff
Whyte Hirschboeck Dudek S.C.
111 E. Wisconsin Ave., Suite 2100
Milwaukee, WI 53202
phone: (414) 273-2100
fax: (414) 223-5000

Respectfully submitted,

MICRON TECHNOLOGY, INC.

Dated: 2/6/02

By: 
Roderic W. Lewis
Vice President-Legal Affairs,
General Counsel and Corporate Secretary



STATEMENT UNDER 37 CFR 3.73(b)

Applicant/Patent Owner: Lee, Teck Kheng

Application No./Patent No.: 10/050,507

Filed/Issue Date: January 16, 2002

Entitled: Elimination of RDL Using Tape Base Flip Chip on Flex for Die Stacking

Micron Technology, Inc.

, a

Corporation

(Name of Assignee)

(Type of Assignee, e.g., corporation, partnership, university, government agency, etc.)

states that it is:

1. ☒ the assignee of the entire right, title, and interest; or
2. ☐ an assignee of an undivided part interest

in the patent application/patent identified above by virtue of either:

- A. ☒ An assignment from the inventor(s) of the patent application/patent identified above. The assignment was recorded in the Patent and Trademark Office at Reel _____, Frame _____, or for which a copy thereof is attached.

OR

- B. ☐ A chain of title from the inventor(s), of the patent application/patent identified above, to the current assignee as shown below:

1. From: _____ To: _____
The document was recorded in the Patent and Trademark Office at
Reel _____, Frame _____, or for which a copy thereof is attached.
2. From: _____ To: _____
The document was recorded in the Patent and Trademark Office at
Reel _____, Frame _____, or for which a copy thereof is attached.
3. From: _____ To: _____
The document was recorded in the Patent and Trademark Office at
Reel _____, Frame _____, or for which a copy thereof is attached.

☐ Additional documents in the chain of title are listed on a supplemental sheet.

- ☐ Copies of assignments or other documents in the chain of title are attached.

(NOTE: A separate copy (i.e., the original assignment document or a true copy of the original document) must be submitted to Assignment Division in accordance with 37 CFR Part 3, if the assignment is to be recorded in the records of the PTO. See MPEP 302-302.8]

The undersigned (whose title is supplied below) is empowered to sign this statement on behalf of the assignee.

2/20/02
Date

Roderic W. Lewis
Signature

Roderic W. Lewis

Typed or printed name

Vice President-Legal Affairs, General Counsel and
Corporate Secretary

Title

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PATENT

Practitioner's Docket No. MTL-31607

For: ☒ U.S. and/or ☒ Foreign Rights
For: ☒ U.S. Application-or ☐ U.S. Provisional Application
For: ☒ U.S. Patent For: ☐ PCT Application
By: ☒ Inventor or ☐ Present-Owner

ASSIGNMENT OF INVENTION (SINGLE INVENTOR)

In consideration of the payment by ASSIGNEE to ASSIGNOR of the sum of One Dollar (\$1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration,

ASSIGNOR:

Teck Kheng Lee

Inventor(s) or person(s) or entity(ies) who own the invention

**Block 687D, Choa Chu Kang Drive, #22-374
Singapore 684687**

Address

Nationality **SG**

hereby sells, assigns and transfers to

ASSIGNEE:

Micron Technology, Inc.

Inventor(s) or person(s) or entity(ies) who own the invention

**8000 S. Federal Way
Boise, Idaho 83706-9632**

Address

and the successors, assigns and legal representatives of the ASSIGNEE
(complete one of the following)

- ☒ the entire right, title and interest
- ☐ an undivided percent (%) interest for the United States and its territorial possessions
- ☒ and in all foreign countries, including all rights to claim priority in and to any and all improvements which are disclosed in the invention entitled:

**Elimination of RDL Using Tape Base Flip
Chip on Flex for Die Stacking**

and which is found in (37 C.F.R. § 3.21)

- (a) ☒ U.S. patent application executed on even date herewith
- (b) ☐ U.S. patent application executed on _____.
- (c) ☐ U.S. provisional application naming the above inventor(s) for the above-entitled invention
- ☐ Express mail label no.:
- Mailed: _____
- ☐ To comply with 37 C.F.R. § 3.21 for recordal of this assignment, I, an ASSIGNOR signing below, hereby authorize and request my attorney to insert below the filing date and application number when they become known.
- (d) ☐ U.S. application no. _____ filed on _____
- (e) ☐ International application no. _____ PCT/ filed on _____
- (f) ☐ U.S. patent no. _____ issued _____
- ☐ A change of address to which correspondence is to be sent regarding patent maintenance fees is being sent separately.

(check (g), if foreign application(s) is also being assigned)

- (g) ☒ and any legal equivalent thereof in a foreign country, including the right to claim priority

and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuation, division, renewal, or substitute thereof, and as to letters patent any reissue or re-examination thereof.

ASSIGNOR hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment.

ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to ASSIGNOR and will testify as to the same in any interference, litigation or proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the purposes thereof.

IN WITNESS WHEREOF, I have hereunto set hand and seal this 5 day of
January, 2002.

WARNING: The date of signing must be the same as the date of execution of the application, if item (a) was checked above.

Date: 1/15/2002


Teck Kheng Lee



WHYTE
HIRSCHBOECK
DUDEK S.C.

111 EAST WISCONSIN AVENUE
SUITE 2100
MILWAUKEE, WI 53202-4894

Assistant Commissioner for Patents
Washington D.C. 20231

